## 普誠科技股份有限公司 Princeton Technology Corp.

### **RX3310A UHF ASK Receiver**

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## **Description**

The RX3310A is a fully integrated, amplitude-shift-keying (ASK) modulation, single chip receiver. It is designed to operate in a variety of low power radio applications. All popular radio frequencies from 250 MHz to 450 MHz may be supported by simply choosing the appropriate external components. Particular emphasis has been placed on low current consumption.

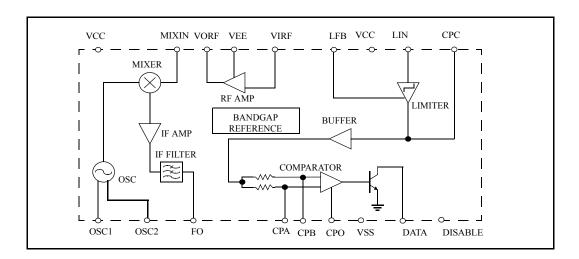
#### **Features**

- ◆ Wide frequency range: 250 MHz to 450 MHz
- High sensitivity
- ◆ Low power consumption
- ◆ Automotive temperature range
- ◆ High integration level requiring few and inexpensive external components
- ◆ SOP 18L package or SSOP 20L (150 mil) package

## **Applications**

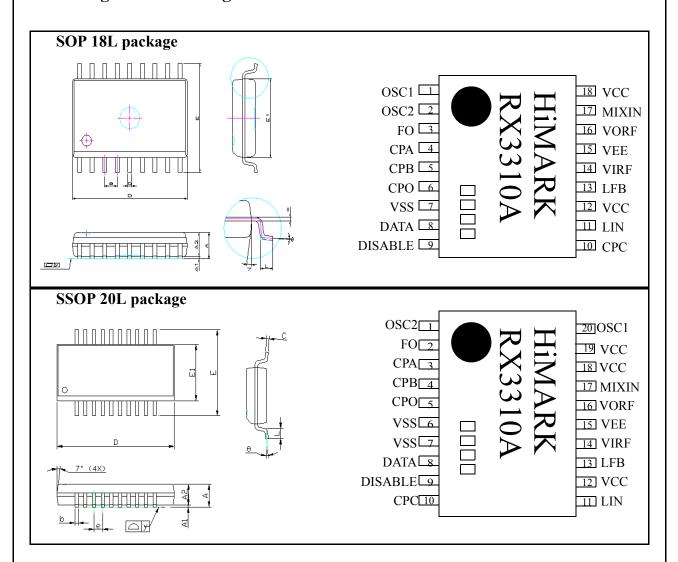
- ◆ Remote control systems
- Car alarm and other security systems
- ◆ Baby finder, wireless doorbell, wireless toys

## **Block Diagram**



Page 1 July 2005

## Package and Pin Assignment: SOP 18L or SSOP 20L



Sym bols	(dim	SOP 18L SOP 18L SSOP 20L (dimensions in inch) (dimensions in mm)			SSOP 20L (dimensions in inch)							
DOIS	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A			2.640			0.104	1.35	1.60	1.75	0.053	0.064	0.069
A1	0.100			0.004			0.1		0.25	0.004		0.010
A2	2.190	2.290	2.390	0.086	0.090	0.094		1.45			0.057	
b	0.360	0.410	0.460	0.014	0.016	0.018	0.20	0.25	0.30	0.008	0.010	0.012
С	0.242	0.250	0.258	0.007	0.010	0.013	0.19		0.25	0.007		0.010
D	11.46	11.56	11.66	0.451	0.455	0.459	8.55		8.75	0.337		0.344

# RX3310A

Sym bols		SOP 18L ensions in			SOP 18L ensions in				SSOP 20L (dimensions in inch)			
DOIS	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
Е	10.04	10.34	10.64	0.395	0.407	0.419	5.80		6.20	0.228		0.244
E1	7.390	7.490	7.590	0.291	0.295	0.299	3.80		4.00	0.150		0.157
e	1.220	1.270	1.320	0.048	0.050	0.052		0.64			0.025	
L	0.640	0.840	1.040	0.025	0.033	0.041	0.40		1.27	0.016		0.050
θ	0°		8°	0°		8°	0°		8°	0°		8°
у			0.050			0.002			0.10			0.004

# **RX3310A Chip Window**

VCC	MIXIN VORF VEE VIRF  LFB  VCC  LIN  CPC	
OSC1	RX3310A DISABLE	
OSC2	FO CPA CPB CPO VSS DATA	

Page 3 July 2005

# **Pin Descriptions**

Number (18L SOP)	Number (20L SSOP)	Name	I/O	Description
1	20	OSC1	IO	Oscillator tank connection
2	1	OSC2	IO	Oscillator tank connection
3	2	FO	О	IF filter output
4	3	СРА	I	Comparator input A
5	4	СРВ	I	Comparator input B
6	5	СРО	I	Comparator offset adjustment
7	6,7	VSS	GND	Ground
8	8	DATA	О	Data output
9	9	DISABLE	I	Disable input. See Electrical Characteristics (cont.) on page 6
10	10	CPC	I	Comparator input C
11	11	LIN	I	Limiter input
12	12	VCC	POWER	Positive supply voltage
13	13	LFB	IO	Limiter feedback B
14	14	VIRF	I	RF amplifier input (requires external ac decoupling capacitor)
15	15	VEE	GND	Ground for RF amplifier
16	16	VORF	О	RF amplifier output
17	17	MIXIN	I	Mixer input (requires external ac decoupling capacitor)
18	18,19	VCC	POWER	Positive supply voltage

# **Absolute Maximum Ratings**

$$V_{SS} = 0 V$$

Parameter	Symbol	Rating	Unit
Supply voltage	V <sub>CC</sub>	$V_{SS} - 0.3 \text{ to } V_{SS} + 6.0$	V
Operating temperature range	$T_{OPR}$	-60 to 85	°C
Storage temperature range	$T_{STG}$	-60 to 125	°C
Soldering temperature range	$T_{SLD}$	255	°C
Soldering time range	$t_{\rm SLD}$	10	S

# **Recommended Operating Conditions**

$$V_{SS} = 0 V$$

Parameter	Symbol		Unit			
i diametei	Symbol	min.	typ.	max.	Oilit	
Supply voltage range	V <sub>CC</sub>	2.0	3.0	6.0	V	
Operating temperature	$T_A$	-40	25	85	°C	

## **Receiver Characteristics**

( $V_{CC}$  = 2.0 to 6.0 V, **LO-RF=1.8MHz**,All tests at  $T_A$  = 25 °C unless otherwise noted)

Parameter	Symbol	Condition		Unit			
1 arameter	Symbol	Condition	min.	typ.	max.	Omt	
Sensitivity	P <sub>sens</sub>	$V_{CC} = 3.0 \text{ V}, T_A = 27 \text{ °C},$ AM 99%, sine wave (ASK square wave)	-100 (-104)	<b>-98</b> (-102)		dBm	
Maximum input power	P <sub>in,max</sub>			-35	-30	dBm	
Receiver turn-on time	t <sub>ON</sub>				5	ms	

## **Electrical Characteristics**

 $(V_{CC} = 3.0 \text{ V}, V_{SS} = 0 \text{ V}, \text{All tests at } T_A = 25 \, ^{\circ}\text{C} \text{ unless otherwise noted})$ 

Parameter	Symbol	Condition		Unit			
i arameter	Symbol	Condition	min.	typ.	max.	Cilit	
Supply current	$I_{CC}$			3	4.5	mA	
Standby current	$I_{CC,sb}$	DISABLE = high		5	10	μΑ	
Disable pin input logic high <sup>a</sup>	$V_{\mathrm{DIH}}$		2.0	2.4		V	
Disable pin input logic low <sup>a</sup>	$V_{ m DIL}$				0.8	V	
Data output logic high	V <sub>OH</sub>		V <sub>pp</sub> b 0.3 V			V	
Data output logic low	V <sub>OL</sub>				0.3	V	

a. Note: If the Disable pad is connected to an off-chip signal (open), then the pad is internally grounded. b. Note:  $V_{\rm pp}$  is the pull-up voltage for open collector data output. It may be as high as 13 V.

# **Electrical Characteristics (cont.)**

 $(V_{CC} = 5.0 \text{ V}, V_{SS} = 0 \text{ V}, \text{All tests at } T_A = 25^{\circ}\text{C} \text{ unless otherwise noted})$ 

Parameter	Symbol	Condition		Unit			
i arameter	Symbol	Condition	min.	typ.	max.	Cilit	
Supply current	$I_{CC}$			4.5	5.0	mA	
Standby current	$I_{CC,sb}$	DISABLE = high		5	10	μΑ	
Disable pin input logic high <sup>a</sup>	$V_{\mathrm{DIH}}$		2.0	2.4		V	
Disable pin input logic low <sup>a</sup>	$V_{ m DIL}$				0.8	V	
Data output logic high	V <sub>OH</sub>		V <sub>pp</sub> b 0.3 V			V	
Data output logic low	$V_{OL}$				0.3	V	

a. Note: If the Disable pad is connected to an off-chip signal (open), then the pad is internally grounded.

b. Note: V<sub>pp</sub> is the pull-up voltage for open collector data output. It may be as high as 13 V.

## **Functional Description**

#### RF amplifier

The RF amplifier uses a common emitter configuration with a separate emitter connection (VEE). The input signal (VIRF) should be ac-coupled externally. The output of the amplifier is open collector so that the gain may be set with an external tuned load.

#### Mixer

The mixer is doubly-balanced configuration and has an ac-coupled input.

#### **Oscillator**

A balanced oscillator configuration is used with an L-C tank externally connected across the OSC1 and OSC2 pins. The frequency of the oscillator is determined by the external capacitor, C1, and inductor, L1 (please refer to application circuit schematic).

### IF amplifier

The IF amplifier is a differential input, single-ended output emitter-coupled pair. It is used to provide additional gain in order to reduce the influence of the noise of the succeeding limiter amplifier on the total receiver noise figure.

#### IF filter

To minimize external component costs, an active IF filter is fully integrated.

#### Limiter

The limiting amplifier consists of several dc-coupled amplifier stages and outputs an RSSI signal.

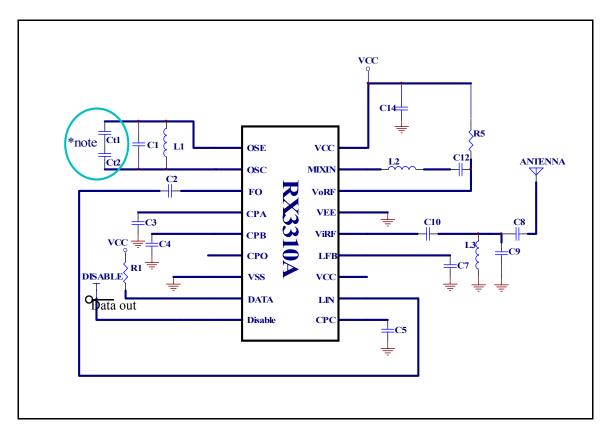
#### Comparator

Following the limiting amplifier, the RSSI signal is passed through an additional buffer stage and is then fed to the comparator's positive and negative terminals, which possess different R-C filter time constants. A larger off-chip capacitor is used at the negative comparator input and hence, its terminal voltage represents the average value of the RSSI signal. A smaller off-chip capacitor is used at the positive comparator input and this allows the positive input to follow the RSSI signal instantaneously. When the received RSSI signal exceeds its average value (when an ASK **on** signal is received), the comparator output is switched on.

#### Band gap reference

A band gap reference provides precise biasing of the entire chip over temperature.

# **Application Circuit SOP 18L**



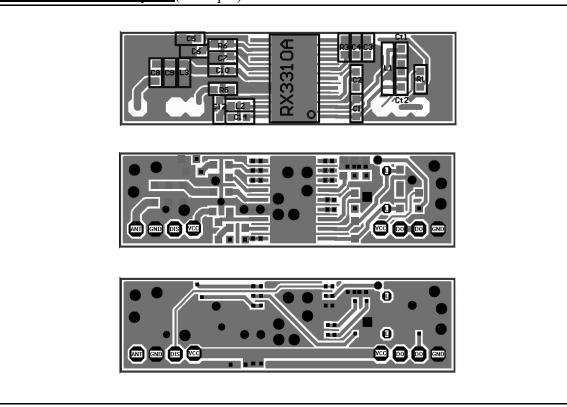
<sup>\*</sup> note:Ct1,Ct2 are added for the temperature compensation. Not necessary.

# **External Components**

Component		Frequency	Band (MHz)		Unit	Tolerance	Remark
Component	303	315	418	434	Oint	Tolerance	Kemark
C1	6.8	6.8	6.8	5.6	pF	+/-0.5pF	TC=NPO
C2	68	68	68	68	pF	+/-5%	TC=NPO
C3	470	470	470	470	pF	+/-10%	TC=X7R
C4	1	1	1	1	μF	+/-10%	TC=Y5V
C5	470	470	470	470	pF	+/-10%	TC=X7R
C7	10	10	10	10	nF	+/-10%	TC=X7R
C8	2.2	1.8	1.8	1.5	pF	+/-0.25pF	TC=NPO
C9	1.8	1.5	1.2	1.2	pF	+/-0.25pF	TC=NPO
C10	22	18	22	10	pF	+/-5%	TC=NPO
C12	82	82	82	82	pF	+/-5%	TC=NPO
C14	1	1	1	1	μF	+/-10%	TC=Y5V
Ct1	3	3	3	3	pF		GRM4DUJ030C50
Ct2	8.2	8.2	8.2	8.2	pF		TC=NPO
R1	100	100	100	100	ΚΩ	+/-5%	TC=+/-200 ppm
R5	1	1	1	1	ΚΩ	+/-5%	TC=+/-200 ppm
L1	2.5	2.5	1.5	1.5	Т		tunable
L2	100	100	100	82	nН		
L3	33	33	18	18	nН		

note: All components are SMD 0805 type.

## **Evaluation Board Layout** (Example)

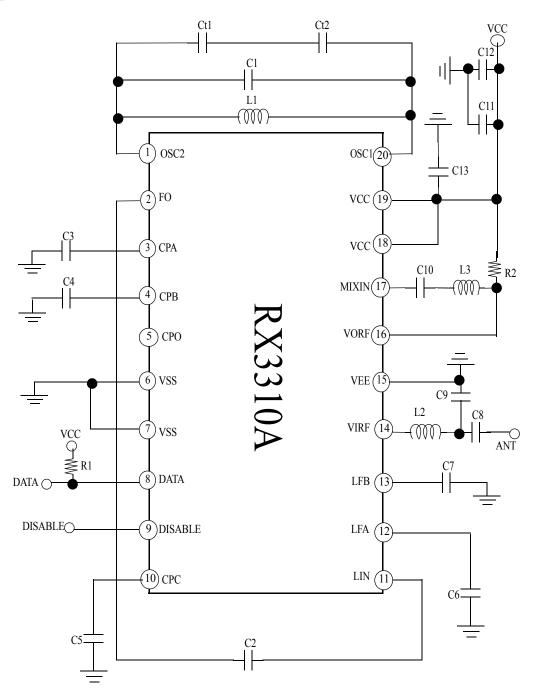


- 1. From top to bottom: Component side of printed-circuit board, top side, bottom side.

  2. Copy this page by the factor of 50%, the real size printed-circuit board is available.(Real-size:11.8mm\*43.5mm)

  3. Suggested board material: FR4, thickness: 0.8mm

# **Application Circuit SSOP 20L**



<sup>\*</sup> note:Ct1,Ct2 are added for the temperature compensation. Not necessary.

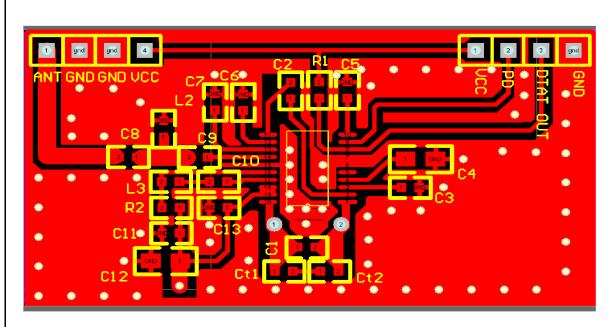
# **External Components**

Component	Frequenc	ey (MHz)	Unit	Tolerance	Remark
Component	315	434	Oiiit	Tolerance	Remark
C1	8.2	6.8	pF	+/-0.5pF	TC=NPO
C2	100	100	pF	+/-5%	TC=NPO
C3	560	560	pF	+/-10%	TC=X7R
C4	1	1	μF	+/-10%	TC=Y5V
C5	1	1	nF	+/-10%	TC=X7R
C6	10	10	nF	+/-10%	TC=X7R
C7	10	10	nF	+/-10%	TC=X7R
C8	100	100	pF	+/-0.25pF	TC=NPO
С9	4.7	8.2	pF	+/-0.25pF	TC=NPO
C10	100	120	pF	+/-5%	TC=NPO
C11	10	10	nF	+/-10%	TC=X7R
C12	3.3	3.3	uF	+/-10%	TC=Y5V
C13	470	470	pF	+/-10%	TC=X7R
Ct1					
Ct2					
R1	100	100	ΚΩ	+/-5%	TC=+/-200 ppm
R2	680	680	Ω	+/-5%	TC=+/-200 ppm
L1	2.5	1.5	Т		tunable
L2	100	56	nН		
L3	100	68	nН		

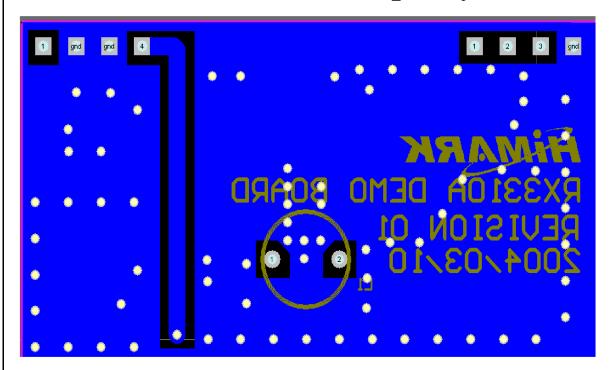
note: All components are SMD 0603 type.

<sup>\*</sup> note:Ct1,Ct2 are added for the temperature compensation. Not necessary.

## **Evaluation Board Layout** (Example)



# RX3310A PCB Top Layer



# RX3310A PCB Bottom Layer

- 1. From top to bottom: Component side of printed-circuit board, top side, bottom side.

  2. The PCB protel file is available. The real size printed-circuit board is available. (Real-size:1753 mil\*934mil)
- 3. Suggested board material: FR4, thickness: 1.0mm

Page 13 July 2005